

REV	LOCATIONS	DESCRIPTION	DATE	REVISED	APPD
1	△	Size change	17/JUL/19	KATE	CHERRY

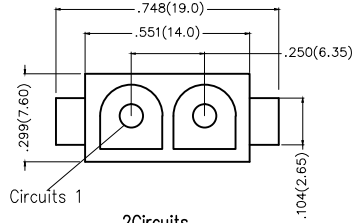
Electrical

Current Rating: 10A AC(rms)/DC
Voltage Rating: 600V AC(rms)/DC
Contact Resistance: 10 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 5000V AC r.m.s
Temperature Range—Operating: -25°C ~ +85°C

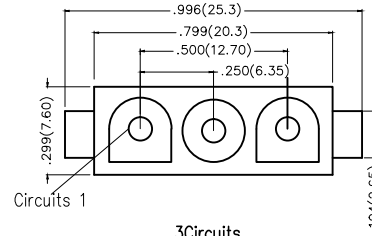
Material and Plating

Housing: PA66(UL 94V-0)
Contact Pin: Brass
Plating: Tin Plated

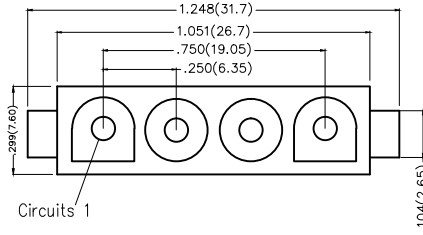
Circuits (n)	Part No.	Dimensions(in./mm)	
		A	
2	FWF63501-S02S22TB	.250(6.35)	
3	FWF63501-S03S22TB	.500(12.70)	
4	FWF63501-S04S22TB	.750(19.05)	
5	FWF63501-S05S22TB	1.00(25.40)	



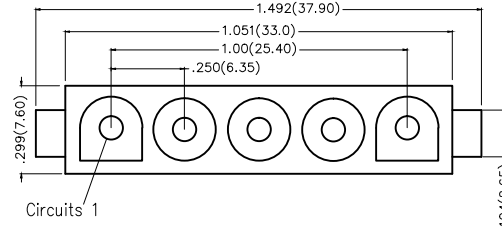
2Circuits



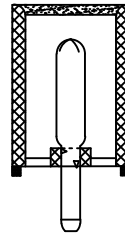
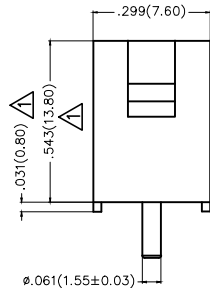
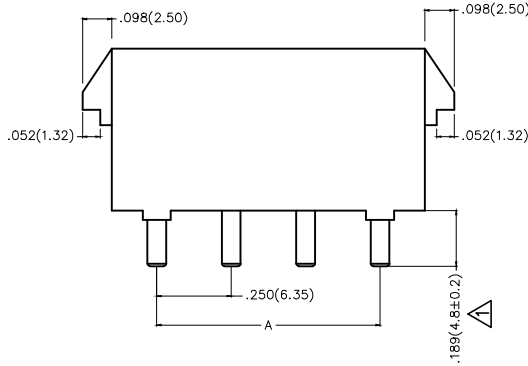
3Circuits



4Circuits



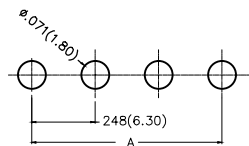
5Circuits




Ordering Information

FWF 635 01 - S XX S 2 2 T B
1 2 3 4 5 6 7 8 9 10

1 Category FWF-Wafer	2 Series Number 635-Pitch6.35mm	3 Distinction No. 01	4 Row Option Single Row	5 Circuits XX	6 Entry Angle S-180°Vertical
7 Plating 2-Tin Plated	8 Material-Resin 2-PA66	9 Color-Resin T-Transparent	10 Packaging B-PE Bag		



Recommended P.C.Board Layout

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF63501-SXXS22TB	ITEM NO. FWF63501	 Leader Of Industry
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X'±5' .X'±2' .XX'±1' .XXX'±0.5'	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 6.35mm 180° Vertical (DIP)	
SCALE 5:1	SIZE A4		DRAWN BY CHERRY	DATE 28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

REV 1 SHEET NO. 1/1